

PATENT 2-4-03

F Docket No.: 50090-290

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

E<sup>MA</sup> Keiichiro WAKAMIYA, et al.

Serial No.: 09/818,906

Filed: March 28, 2001

For: SEMICONDUCTOR DEVICE

RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE

Group Art Unit: 2811

Examiner: Nitin Parekh

Intered. J. manuelas 5/31/03

## **AMENDMENT UNDER 37 CFR § 1.116**

Box AF Commissioner for Patents Washington, DC 20231

Sir:

The following Amendment and Remarks is submitted in response to the Office Action dated November 20, 2002 pursuant to the provisions of 37 CFR § 1.116.

## IN THE CLAIMS:

Please amend claims 1 and 7 as follows:

- 1. (Twice Amended) A semiconductor device comprising:
- a semiconductor chip,
- a protective insulating layer <u>comprising a coating layer</u> covering the surface of the semiconductor chip;
- a plurality of connecting conductors connected to the surface of the semiconductor chip and penetrating the [protective insulating] coating layer beyond the outside surface of the [protective insulating] coating layer;